University of California at Berkeley College of Engineering Dept. of Electrical Engineering and Computer Sciences

EE 105 Midterm I

Spring 2002

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Guidelines

Closed book and notes; one 8.5" x 11" page (both sides) of *your own notes* is allowed. You may use a calculator.

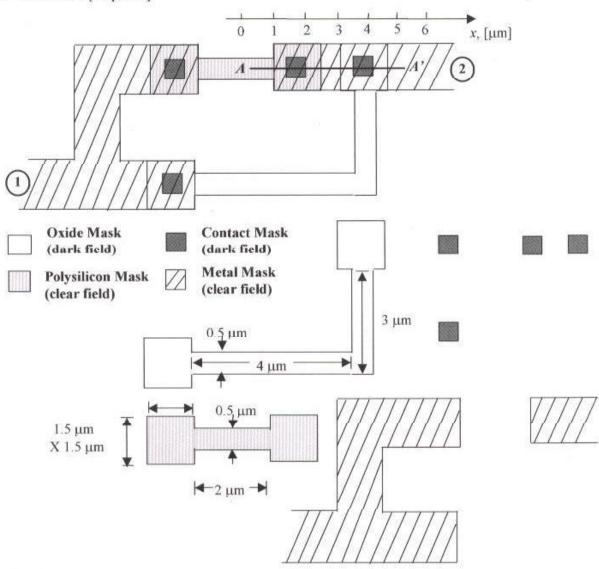
Do not unstaple the exam.

Show all your work and reasoning on the exam in order to receive full or partial credit.

Score

Problem	Points Possible	Score
1	17	
2	17	
3	16	
Total	50	

1. IC resistors [17 points]



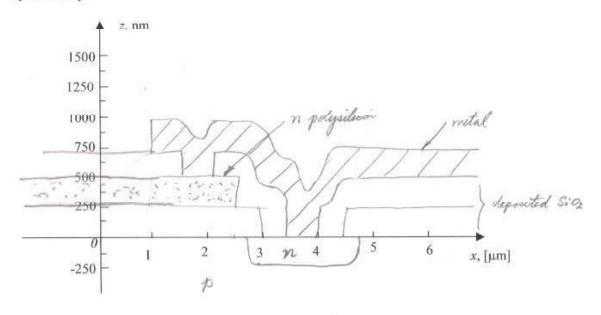
Process Sequence:

- 1. Starting material: p-type silicon wafer with a doping concentration of 1 x 10¹⁶ cm⁻³
 2. Deposit a 250 nm-thick SiO₂ layer
- 2. Deposit a 250 nm-thick SiO₂ layer
- 3. Deposit a 250 nm-thick layer of n-type polysilicon and pattern using the Polysilicon Mask (clear field).
- 4. Pattern the oxide using the Oxide Mask (dark field).
 5. Implant phosphorus with dose Q_d = 5 x 10¹² cm⁻² and anneal to form a 250 nm thick phosphorus-doped region.
- Deposit a 250 nm-thick SiO₂ layer and pattern using the Contact Mask (dark field).
- Deposit 0.5 μm of aluminum and pattern using the Metal Mask (clear field).

250 nm

Given: mobilities for this problem are $\mu_n = 500 \text{ cm}^2/(\text{Vs})$ and $\mu_p = 200 \text{ cm}^2/(\text{Vs})$ for both silicon and polysilicon). The saturation electric field for electrons in polysilicon or silicon is $E_{sat} = 2 \times 10^4 \text{ V/cm}$ and their saturation velocity is $v_{sat} = 10^7 \text{ cm/s}$. The mobile electron concentration in the polysilicon is $n = 10^{17} \text{ cm}^{-3}$ at the end of the process. Count the "dogbone" contact areas as 0.65 square each and the corner square as 0.56 squares in finding the resistance.

(a) [5 pts.] Sketch the cross section A-A' on the graph below after step 7. Identify all layers clearly.



(b) [3 pts.] What is the sheet resistance R_{\odot} of the 0.25 μ m-thick silicon region formed in step 5?

$$R_{\Box} = \frac{f_{n}}{t} = \frac{1}{9(N_{d} - N_{a})\mu_{n}t} = \frac{1}{(1.6 \times 10^{1/5})(2-1) \times (0^{1/5})(5 \times 10^{2})(4 \times 10^{-4})}$$

$$N_{d} = \frac{Q_{d}}{t} = \frac{5 \times 10^{12} cm^{-2}}{\frac{1}{4} \times 10^{-4} cm} = 2 \times 10^{17} cm^{-3} = \frac{10^{4}}{(1.6 \times 5)/4} = 5000 \, \text{D}/\Box$$

$$R_{\Box} = 5 \, \text{keV}/\Box.$$

(c) [3 pts.] What is the maximum current
$$I_{max}$$
 in μ A resistance through the polysilicon resistor?

$$I_{max} = I_{max} - W_{s}t_{p} - W_{s}t_{p} = (g n v_{max})(1.25 \times 10^{-3} cm^{2}) = 2 \times 10^{-4} A$$

$$10^{17} cm^{-3}$$

$$I_{max} = 200 \mu A$$

(d) [4 pts.] Plot the current-voltage curve between terminals 1 and 2 over the range indicated on the graph below.

I on the graph below.

POLY

RESISTOR:

$$V_{mog} = (I_{max}) \cdot R_{pv} g = (200\mu A)(26.5450)$$

$$= 5.3V$$

$$= 80, = 5kQ/D$$

$$ND = (2/0.5) + 2(0.65)$$

$$= 5.3$$

$$= 707aL$$

$$CURRENT$$

$$= 700 \cdot V_{mog} = (I_{max}) \cdot R_{pv} g = (200\mu A)(26.5450)$$

$$= 5.3V$$

$$= 707aL$$

$$= 7$$

(e) [3 pts.] The total voltage between terminals 1 and 2 is:

2

0

$$V_{12}(t) = V_{DC} + v_{ac} \cos(\omega t)$$

$$R_{hc} = 74.3 \text{ A.Q.}$$

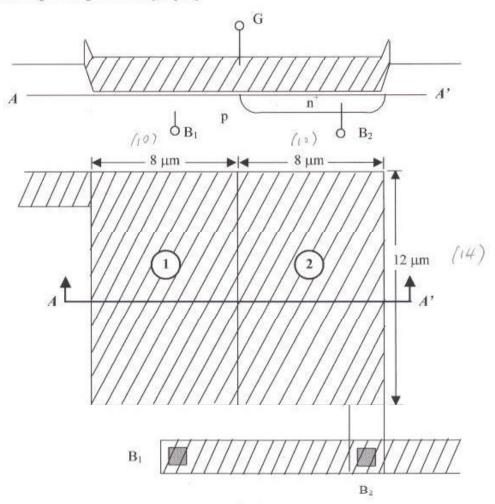
with $V_{DC} = 2.5 \text{ V}$ and $v_{ac} = 5 \text{ mV}$. What is the small-signal component of the current between terminals 1 and 2?

$$r = \frac{\partial V_{12}}{\partial V_{12}} \Big|_{V_{DC}} = R_n = 74.34\Omega$$

$$\dot{v}_n = \frac{5mV}{74.34\Omega} = 67nA$$

= 14.86 0

2. MOS charge-storage element [17 pts.]



The MOS structure shown in cross section and top view above has a metal gate and two bottom electrodes, B_1 (p substrate) and B_2 (n⁺ layer). The bottom electrodes are contacted by a metal line and shorted together, as indicated on the top view. The oxide thickness is $t_{ox} = 10$ nm for the MOS structure. $C_{ox} = 3.45 \times 10^{-13}$ F/cm.

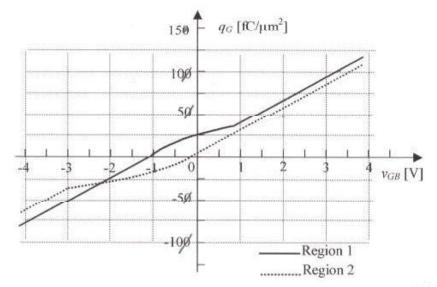
In region 1, the p-type substrate is the bottom electrode and the MOS parameters are:

$$V_{FB} = -1.2 \text{ V}, V_{Tn} = 0.8 \text{ V}$$

In region 2, the n⁺ layer is the bottom electrode and the MOS parameters are:

$$V_{FB} = -0.2 \text{ V}, V_{Tp} = -3 \text{ V}$$

The charge storage curves for the two regions are provided on the graphs below of gate charge per unit area versus the gate-bottom electrode potential, v_{GB} . Since $B_1 = B_2$, we use "B" to represent the potential of the bottom electrode for each region.



(a) [4 pts.] For $v_{GB} = 1$ V, find the total charge on the gate (units: femtoCoulombs = 10^{-15} C).

 $g_{61} \approx 4 f c / m^2$ } $g_{6707} = g_{61} A_1 + g_{62} A_2$ = $(4 f c / m^2)(8 \times 12 / m^2) + (3 f c / m^2)(8 \times 12 / m^2)$ = (950 f c)

(b) [4 pts.] For $v_{GB} = -1.5$ V, identify the substrate charge in regions 1 and 2 by circling the correct description(s). Note: the correct answer may have more than one description circled.

Region 1. ionized acceptors accumulated holes inversion-layer electrons

Region 2. ionized donors accumulated electrons inversion-layer holes

(c) [4 pts.] For $v_{GB} = +1.5$ V, identify the substrate charge in regions 1 and 2 by circling the correct description(s). Note: the correct answer may have more than one description circled.

Region 1. ionized acceptors accumulated holes inversion-layer electrons

Region 2. ionized donors accumulated electrons inversion-layer holes

(d) [3 pts.] If we apply a voltage $v_{GB}(t) = 0 \text{ V} + v_{gb}\cos(\omega t)$, where $v_{gb} = 5 \text{ mV}$ and $\omega = 2\pi(10^6)$ rad/s, estimate the current $i_{gb}(t)$ into the gate terminal in nA from the charge-storage curves.

acc. $C_{gb_2} = C_{0x} A_2 = \left[\frac{3.45 \times 10^{-13} F \text{ km}}{1.15 \times 10^{-6} \text{ cm}}\right] \left[8 \times 12 \times 10^{-8} \text{ cm}^2\right] = 288 \text{ ff}$ depletion $C_{gb_1} = \frac{966}{9 \text{ Vos}} A_1 \approx \left(\frac{2.5 \text{ fc/pm}^2}{2 \text{ V}}\right) \left(96 \text{ pm}^2\right) = 120 \text{ ff}$ $C_{gb} = \left[2\pi \left(106\right) \left(5 \text{ mV}\right) \left(408 \text{ ff}\right)\right] \sin \omega t = \left(12.8 \text{ nA}\right) \sin \omega t$ (595)

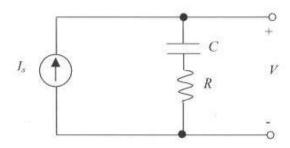
(e) [2 pts.] The maximum capacitance of the MOS structure is C_{max} . If the DC (-18.7) component of v_{GB} is 1.5 V, what is the maximum amplitude of its small-signal component v_{gb} for which the current remains exactly proportional to C_{max} .

$$V_{GB} = 1.5 \text{ V} + v_{gb} \cos \omega t$$

$$V_{GB} = 0.8 \text{ V} = V_{Th} \quad \text{for} \quad \frac{\partial g_{G1}}{\partial v_{GB}} = C_{Ox} A_1 \Rightarrow C = C_{max}$$

$$\delta_0 \quad v_{gb} \leq 700 \, \text{mV}$$

3. Impedance measurements [16 pts.]



The capacitance C = 1 pF and the resistance $R = 1000 \Omega$.

(a) [4 pts.] Find an expression for the impedance $Z = V/I_s$. Your result should contain the term $(1 + j \omega \tau)$.

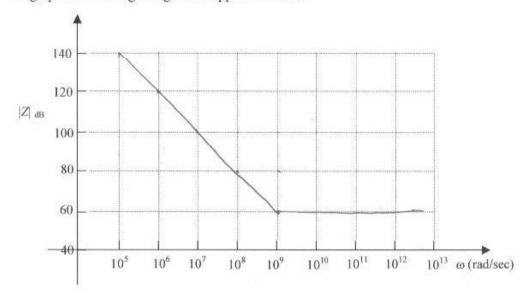
$$Z = \frac{1}{j\omega c} + R = \left(\frac{1}{j\omega c}\right)(1 + j\omega Rc)$$

$$= \left(\frac{R}{j\omega \tau}\right)(1 + j\omega t) = R \left\{\frac{1 + j\omega \tau}{j\omega \tau}\right\}$$

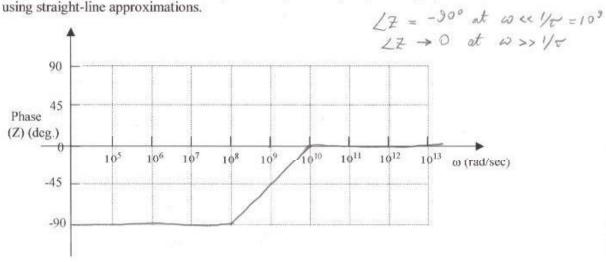
$$\tau = 10^{-9} s$$

$$R = 1 k s v$$

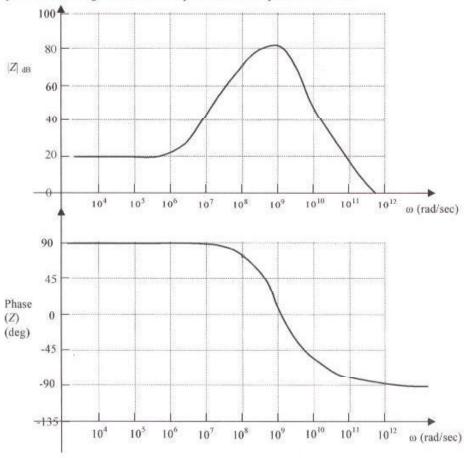
(b) [4 pts.] Sketch the magnitude Bode plot for the impedance Z (units: $20 \log_{10}(\Omega)$) on the graph below using straight-line approximations.



(c) [4 pts.] Sketch the phase of the impedance Z (units: degrees) on the graph below using straight-line approximations.



(d) [4 pts.] You hook up another two-terminal circuit and measure its impedance. The Bode plots of the magnitude and the phase of Z are plotted below.



If a phasor current $I_s = (2.5 \mu A)e^{j(0)}$ what is the voltage waveform v(t) based on the information in the Bode plots? the information in the Bode plots?

tion in the Bode plots?
$$|Z| = 3.16 \text{ A} \Omega$$

$$|Z| = 70 \text{ dB}$$

$$|Z| = 70^{8} \text{ rads}^{-1}$$

$$|Z| = 70^{9}$$

$$|Z| = 70^{9}$$